

WIRE ETCHING METHOD

Patent number: JP2298280
Publication date: 1990-12-10
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Classification:
- international: B24B27/06; C23F1/00
- european:
Application number: JP19890118123 19890511
Priority number(s): JP19890118123 19890511

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Abstract of JP2298280

PURPOSE:To conveniently, easily and precisely work a material into a smooth finished surface free of burrs by pressing the material on the side surface of a wire coated with a liq. etchant and traveling in its longitudinal direction and instantaneously heating the material with the frictional heat.

CONSTITUTION:The wire 2 of pure titanium, etc., is traveled in direction of the arrow at a specified tension by the upper and lower wheels 7 and 8 and idler 13 and passed through the hole of a table 6. The wire 2 is further passed through a vessel 5 contg. a liq. etchant 3, and the whole periphery is uniformly coated by a coating member 4. The member 1 to be worked is pressed on the side surface of the wire 2 and instantaneously heated by the frictional heat. The contact part between the material 1 and the wire 2 is eluted by the heated etchant 3, and the etchant is washed off by cleaning water 9. The wire 2 is then dried by a hot-air drier 11. The material 1 is worked by this simple device and excellently finished.

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